

PRECISION, GAIN OF 0.2 LEVEL TRANSLATION DIFFERENCE AMPLIFIER

FEATURES

 Gain of 0.2 to Interface ±10-V Signals to Single-Supply ADCs

Gain Accuracy: ±0.024% (max)
 Wide Bandwidth: 1.5 MHz
 High Slew Rate: 15 V/μs
 Low Offset Voltage: ±100 μV

Low Offset Drift: ±1.5 μV/°C

Single-Supply Operation Down to 1.8 V

APPLICATIONS

- Industrial Process Controls
- Instrumentation
- Differential to Single-Ended Conversion
- Audio Line Receivers

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (–55°C/125°C)
 Temperature Range⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability
- (1) Additional temperature ranges are available contact factory

DESCRIPTION

The INA159 is a high slew rate, G = 1/5 difference amplifier consisting of a precision op amp with a precision resistor network. The gain of 1/5 makes the useful to couple ±10-V signals to single-supply analog-to-digital converters (ADCs), particularly those operating on a single +5-V supply. The on-chip resistors are laser-trimmed for accurate gain and high common-mode rejection. Excellent temperature coefficient of resistance (TCR) tracking of the resistors maintains gain accuracy and common-mode rejection over temperature. The input common-mode voltage range extends beyond the positive and negative supply rails. It operates on a total of 1.8-V to 5.5-V single or split supplies. The INA159 reference input uses two resistors for easy mid-supply or reference biasing.

The difference amplifier is the foundation of many commonly-used circuits. The INA159 provides this circuit function without using an expensive external precision resistor network. The INA159 is available in an MSOP-8 surface-mount package and is specified for operation over the extended industrial temperature range, –55°C to 125°C.



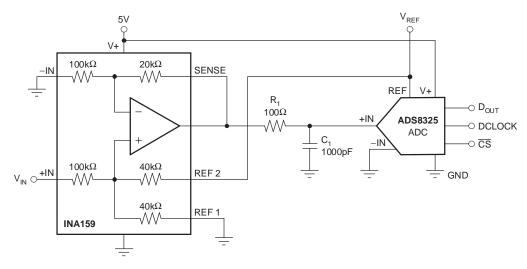


Figure 1. Typical Application



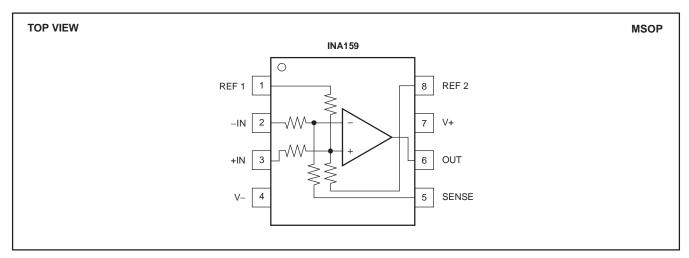
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION(1)

TEMPERATURE	ORDERABLE PART NUMBER ⁽²⁾	PACKAGE LEAD	PACKAGE DESIGNATOR	TOP-SIDE MARKING	
-55°C to 125°C	INA159AMDGKTEP	MSOP-8 Tape and reel	DGK	OAA	

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage			+5.5	V
Signal input terminals (-IN and +IN), voltage			±30	V
Reference (REF 1 and REF2) and sense pins	Current		±10	mA
	Voltage	(V-) - 0.5	(V+) + 0.5	V
Output short circuit			Continuous	
Operating temperature		-55	+125	°C
Storage temperature		-65	+150	°C
Junction temperature			+150	°C
ESD rating	Human-Body Model		4000	V
	Charged-Device Model		1000	V

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.

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ELECTRICAL CHARACTERISTICS

Boldface limits apply over the specified temperature range, $T_A = -55^{\circ}C$ to +125°C. At $T_A = +25^{\circ}C$, $R_L = 10$ k Ω connected to $V_S/2$, REF pin 1 connected to ground, and REF pin 2 connected to $V_{REF} = 5$ V, unless otherwise noted.

PARAMETER	CONDITIONS		INA159			
	CONDITIONO	MIN	TYP MA	X		
OFFSET VOLTAGE ⁽¹⁾	RTO					
Initial ⁽¹⁾ V_{O}	$V_S = \pm 2.5 \text{ V}$, Reference and Input Pins Grounded		±100 ±50	0 μV		
Over Temperature			±145	0 μ V		
vs Power Supply PSRI	$V_{S} = \pm 0.9 \text{ V to } \pm 2.75 \text{ V}$		±20 ±10	0 μV/V		
Over Temperature PSRI	$V_S = \pm 0.9 \text{ V to } \pm 2.75 \text{ V}$		±20	0 μV/V		
Reference Divider Accuracy (2)			±0.002 ±0.02	4 %		
over Temperature			±0.002 ±0.05	0 %		
INPUT IMPEDANCE (3)						
Differential			240	kΩ		
Common-Mode			60	kΩ		
INPUT VOLTAGE RANGE	RTI					
Common-Mode Voltage Range V _{CI}	и					
Positive			17.5	V		
Negative			-12.5	V		
	$V_{CM} = -10 \text{ V to } +10 \text{ V}, R_S = 0 \Omega$	80	96	dB		
over Temperature	- Givi Te Te Te T, Cg = E	74	94	dB		
OUTPUT VOLTAGE NOISE (4)	RTO					
f = 0.1 Hz to 10 Hz	1112		10	μVPP		
f = 10 kHz			30	nV/√Hz		
GAIN	$V_{REF2} = 4.096 \text{ V},$ R_L Connected to GND, $(V_{IN+}) - (VIN-) = -10 \text{ V}$ to +10 V, $V_{CM} = 0 \text{ V}$					
Initial (6		0.2	V/V		
Error			±0.005 ±0.02	4 %		
vs Temperature			±0.03	5 %		
Nonlinearity			±0.0002	% of FS		
OUTPUT						
Voltage, Positive	V _{REF2} = 4.096 V, R _L Connected to GND	(V+) - 0.1	(V+) - 0.02	V		
over Temperature		(V+) - 0.2		٧		
Voltage, Negative	V _{REF2} = 4.096 V, R _L Connected to GND	(V-) + 0.048	(V–) + 0.01	V		
over Temperature		(V-) + 0.070		V		
Current Limit, Continuous to Common			±60	mA		
Capacitive Load		See Typic	al Characteristic	pF		
Open-Loop Output Impedance R	f = 1 MHz, I _O = 0		110	Ω		
FREQUENCY RESPONSE	-					
Small-Signal Bandwidth	-3 dB		1.5	MHz		
Slew Rate SI			15	V/µs		
	S 4 V Output Step, C _L = 100 pF		1	μs		

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 ⁽¹⁾ Includes effects of amplifier input bias and offset currents.
 (2) Reference divider accuracy specifies the match between the reference divider resistors using the configuration in Figure 2.

⁽³⁾ Internal resistors are ratio matched but have 20% absolute value.

⁽⁴⁾ Includes effects of amplifier input current noise and thermal noise contribution of resistor network.

ELECTRICAL CHARACTERISTICS (continued)

Boldface limits apply over the specified temperature range, $T_A = -55^{\circ}C$ to +125°C. At $T_A = +25^{\circ}C$, $R_L = 10$ kΩ connected to $V_S/2$, REF pin 1 connected to ground, and REF pin 2 connected to $V_{REF} = 5$ V, unless otherwise noted.

DADAMETED	CONDITIONS	IN	LINUT		
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Overload Recovery Time	50% Overdrive		250		ns
POWER SUPPLY					
Specified Voltage Range V _S				+5	V
Operating Voltage Range		+1.8		+5.5	V
Quiescent Current I _Q	$I_O = 0$ mA, $V_S = \pm 2.5$ V, Reference and Input Pins Grounded		1.1	1.5	mA
over Temperature				2.0	mA
TEMPERATURE RANGE					
Specified Range		– 55		+125	°C
Operating Range		– 55		+125	°C
Storage Range		-65		+150	°C
Thermal Resistance θJA					
MSOP-8	Surface Mount		150		°C/W

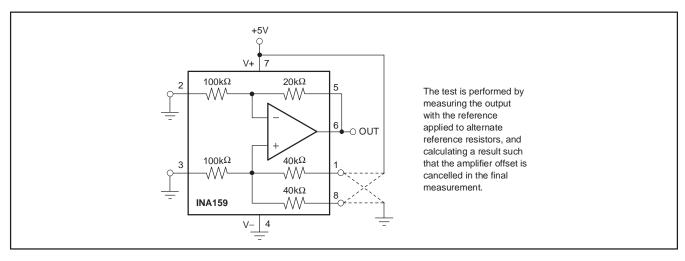


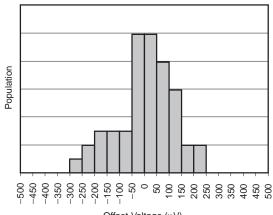
Figure 2. Test Circuit for Reference Divider Accuracy

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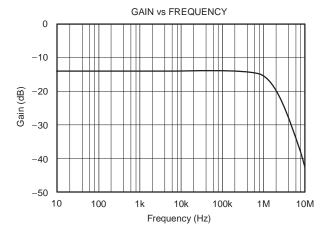
TYPICAL CHARACTERISTICS

At T_A = +25°C, R_L = 10 k Ω connected to $V_S/2$, REF pin 1 connected to ground, and REF pin 2 connected to V_{REF} = 5 V, unless otherwise noted.

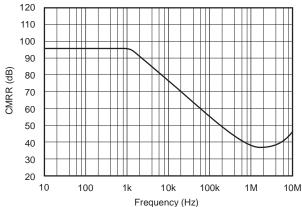




Offset Voltage (µV)

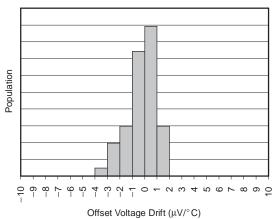


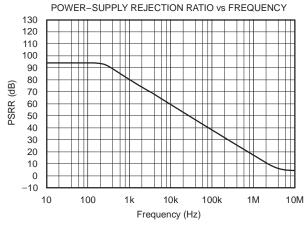
COMMON-MODE REJECTION RATIO vs FREQUENCY



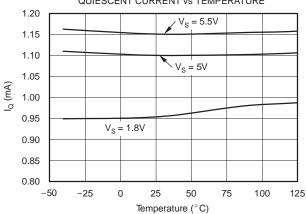
OFFSET VOLTAGE DRIFT PRODUCTION DISTRIBUTION

ISTRUMENTS





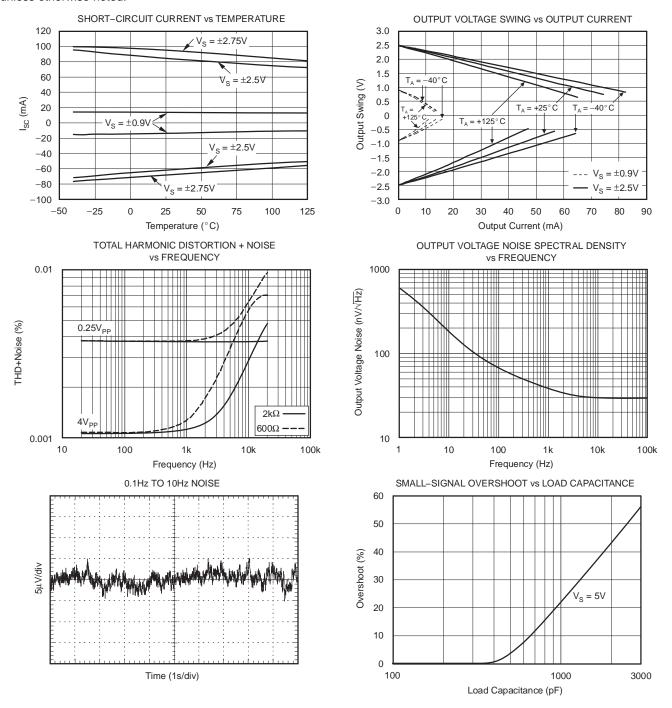
QUIESCENT CURRENT vs TEMPERATURE





TYPICAL CHARACTERISTICS (continued)

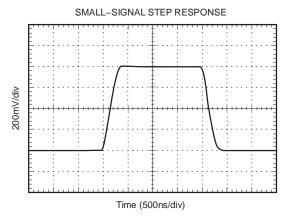
At T_A = +25°C, R_L = 10 k Ω connected to $V_S/2$, REF pin 1 connected to ground, and REF pin 2 connected to V_{REF} = 5 V, unless otherwise noted.

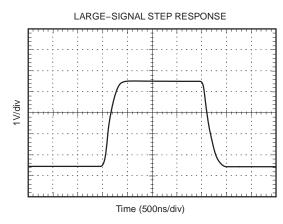


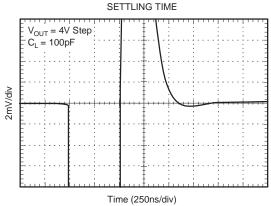


TYPICAL CHARACTERISTICS (continued)

At T_A = +25°C, R_L = 10 k Ω connected to $V_S/2$, REF pin 1 connected to ground, and REF pin 2 connected to V_{REF} = 5 V, unless otherwise noted.







APPLICATION INFORMATION

The internal op amp of the INA159 has a rail-to-rail common-mode voltage capability at its inputs. A rail-to-rail op amp allows the use of ± 10 -V inputs into a circuit biased to 1/2 of a 5-V reference (2.5-V quiescent output). The inputs to the op amp will swing from approximately 400 mV to 3.75 V in this application.

The unique input topology of the INA159 eliminates the input offset transition region typical of most rail-to-rail complementary stage operational amplifiers. This allows the INA159 to provide superior glitch- and transition-free performance over the entire common-mode range.

Good layout practice includes the use of a $0.1-\mu F$ bypass capacitor placed closely across the supply pins.

COMMON-MODE RANGE

The common-mode range of the INA159 is a function of supply voltage and reference. Where both pins, REF1 and REF2, are connected together:

$$V_{CM+} = (V+) + 5[(V+) - V_{REF}]$$
 (1)

$$V_{CM-} = (V-) - 5[V_{REF} - (V-)]$$
 (2)

Where one REF pin is connected to the reference, and the other pin grounded (1/2 reference connection):

$$V_{CM+} = (V+) + 5[(V+) - (0.5V_{REF})]$$
 (3)

$$V_{CM-} = (V-) - 5[(0.5V_{REF}) - (V-)]$$
 (4)

Some typical values are shown in Table 1.

Table 1. Common-Mode Range For Various Supply and Reference Voltages

REF 1 and REF 2 Connected Together									
V+	V-	V _{REF}	V _{CM+}	V _{CM} -					
5	0	3	15	-15					
5	0	2.5	17.5	-12.5					
5	0	1.25	23.75	-6.25					
1/2 Reference	1/2 Reference Connection								
V+	V-	V_{REF}	V _{CM+}	V _{CM} -					
5	0	5	17.5	-12.5					
5	0	4.096	19.76	-10.24					
5	0	2.5	23.75	-6.25					
3.3	0	3.3	11.55	-8.25					
3.3	0	2.5	13.55	-6.25					
3.3	0	1.25	16.675	-3.125					



Input and Output Relationships for Various Reference and Connection Combinations

V _{REF} (V)	REF CONNECTION	V_{OUT} for $V_{IN} = 0$ (V)	LINEAR V _{IN} RANGE (V)	USEFUL V _{OUT} SWING (V)
5	5V Ο V+ 100kΩ 20kΩ 0=140=	2.5	+10 0 -10	4.5 (±2V swing) 0.5
4.096	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.048	10 0 –10	4.048 (±2V swing) 0.048
3.3	OUT	1.65	+10 0 -7.885	3.65 (–1.577V, +2V swing) 0.048
2.5	$V_{\text{IN}} \circ \stackrel{+\text{IN}}{\longrightarrow} 100 \text{k}\Omega$ $00 \text{k}\Omega$ $00 \text{k}\Omega$ $00 \text{k}\Omega$ $00 \text{k}\Omega$ $00 \text{k}\Omega$ $00 \text{k}\Omega$	1.25	+10 (also +5) 0 -6 (also -5)	3.25 (–1.2V, +2V swing) 0.048
1.8	INA159 REF 1	0.9	+10 0 -4.26	2.9 (-0.852V, +2V swing) 0.048
2.5	5V V+	2.5	+10 0 -10	4.5 (= 2V swing) 0.5
1.8	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	1.8	+10 0 -8.76	3.8 (–1.752V, +2V swing) 0.048
1.2	$V_{\text{IN}} \bigcirc +\text{IN}$ 100k Ω 40k Ω REF 2 V_{REF} 40k Ω REF 1	1.2	+10 0 -5.76	3.2 (–1.15V, +2V swing) 0.048



 V_{REF} 5V $100k\Omega$ $20k\Omega$ SENSE ₩ ₩ REF R_1 -⊙ D_{OUT} 100Ω +IN ADS8325 ₩ O DCLOCK ADC C₁ ⊙ cs 1000pF 100kΩ 40kΩ V_{IN} O+IN REF 2 GND ₩ ₩ $40k\Omega$ REF 1 \neg INA159

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Figure 3. Typical Application Circuit Interfacing to Medium-Speed, Single-Supply ADCs

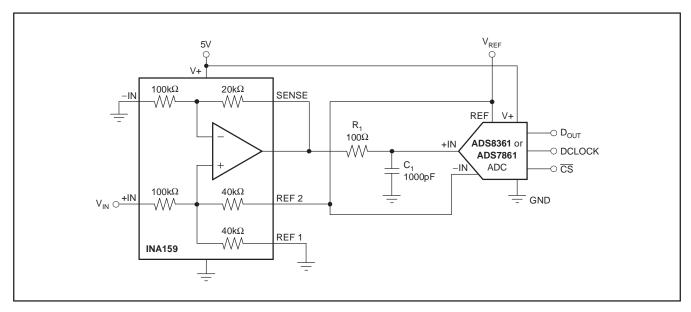


Figure 4. Typical Application Circuit Interfacing to Medium-Speed, Single-Supply ADCs with Pseudo-Differential Inputs (such as the ADS7861 and ADS8361)

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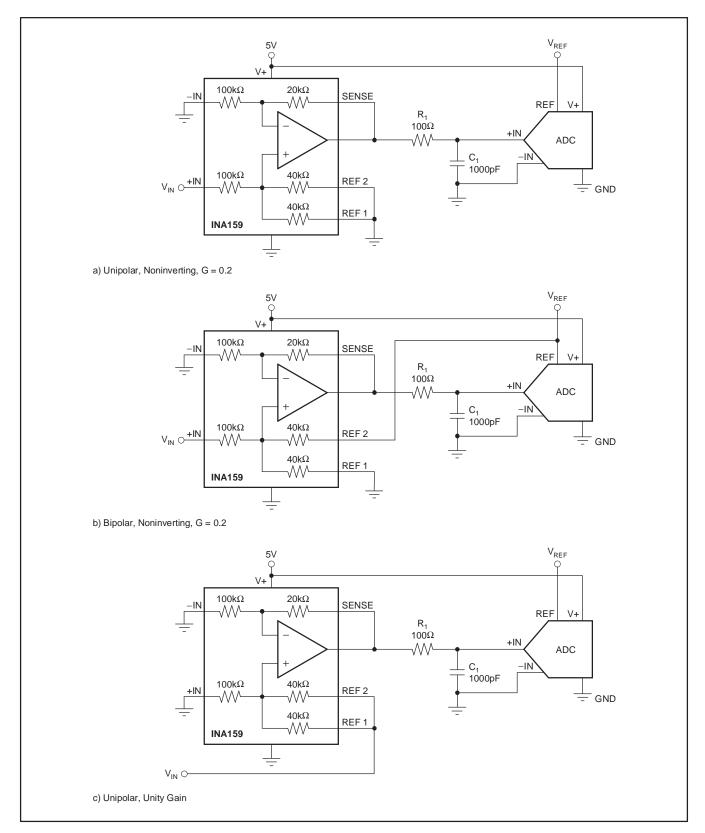


Figure 5. Basic INA159 Configurations



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5V $100 k \Omega$ $20 \text{k}\Omega$ SENSE A -IN A √\/\-V_{IN-} O- 100Ω OUT A ₩ 1000pF $100 \text{k}\Omega$ $40 \text{k}\Omega$ +IN A REF 2A ₩ V_{IN+} O- $40 \mathrm{k}\Omega$ REF 1A -WV-INA159 $\mathrm{V}_{\mathrm{REF}}$ +IN REF 100kΩ --//\/-20kΩ -√√ -IN B SENSE B ADC 100Ω OUT B ₩ 1000pF GND $100 k \Omega$ +IN B REF 2B ₩ ₩ $40 \text{k}\Omega$ REF 1B ₩ **INA159**

Figure 6. Differential ADC Drive





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
INA159AMDGKTEP	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/09613-01XE	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Catalog: INA159

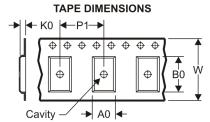
NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA	A159AMDGKTEP	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA159AMDGKTEP	MSOP	DGK	8	250	190.5	212.7	31.8

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



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